

## ESD9B5VLD

**1-Line, Bi-directional, Low-Capacitance,  
Transient Voltage Suppressor**

<http://www.sh-willsemi.com>

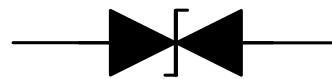
### Descriptions

The ESD9B5VLD is a Bi-directional transient voltage suppressor (TVS) to protect sensitive electronic components from electrostatic discharge (ESD). It is particularly well-suited for cellular phones, PMP, MID, PDA, digital cameras and other electronic equipment.



SOD-923

The ESD9B5VLD is safely dissipating ESD strikes to meet the ESD immunity testing of IEC61000-4-2 level 4.



Pin configuration

### Features

- Reverse stand-off voltage : 5V Max.
- Peak power ( $t_p=8/20\mu s$ ) : 36W Max.
- Peak current ( $t_p=8/20\mu s$ ) : 3A Max.
- Transient protection  
IEC61000-4-2 :  $\pm 20KV$  air  
:  $\pm 20KV$  contact
- Low clamping voltage
- Low leakage current
- Small package



SOD-923

L = Device code  
Marking

### Order information

### Applications

- Cell phone
- PMP
- MID
- PDA
- Digital camera
- Other electronics equipment

Device	Package	Shipping
ESD9B5VLD-2/TR	SOD-923	10000/Tape&Reel

**Absolute maximum ratings**

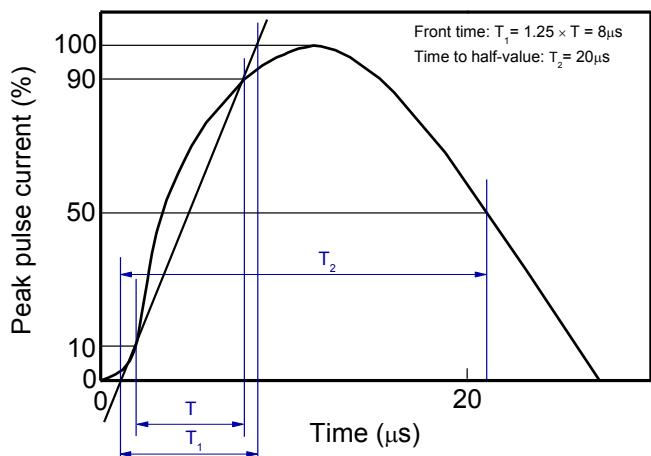
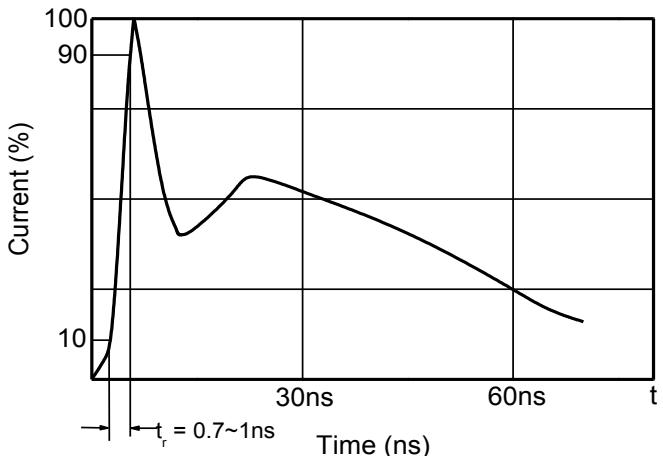
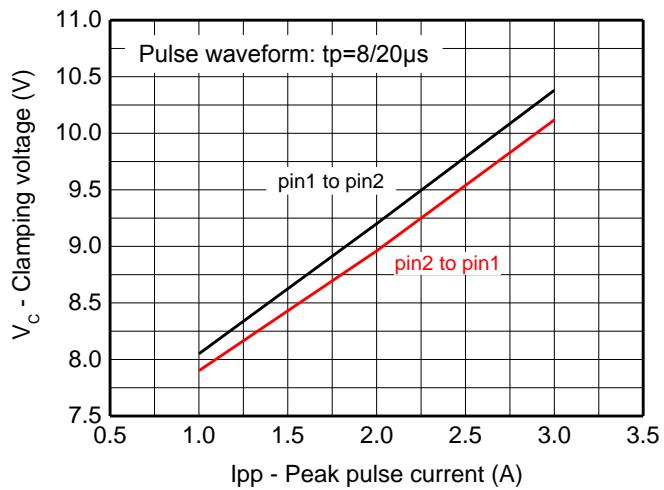
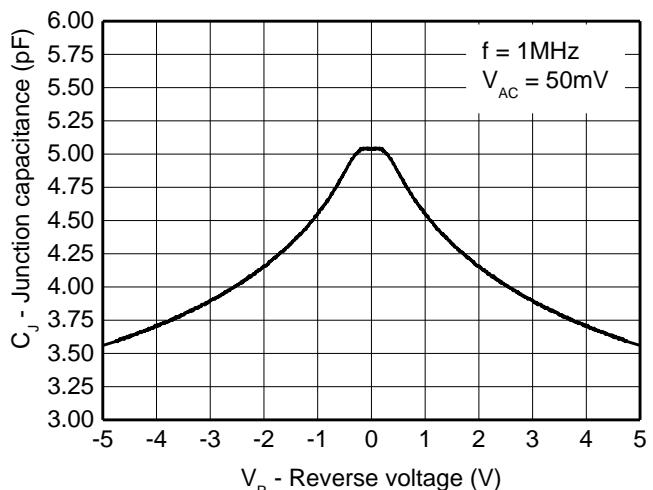
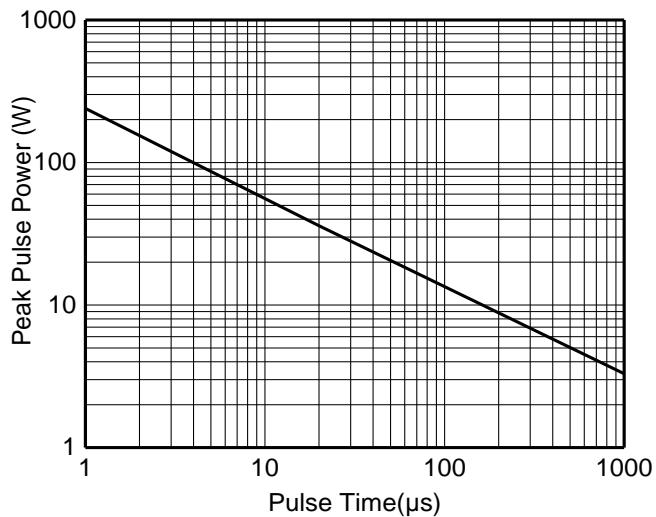
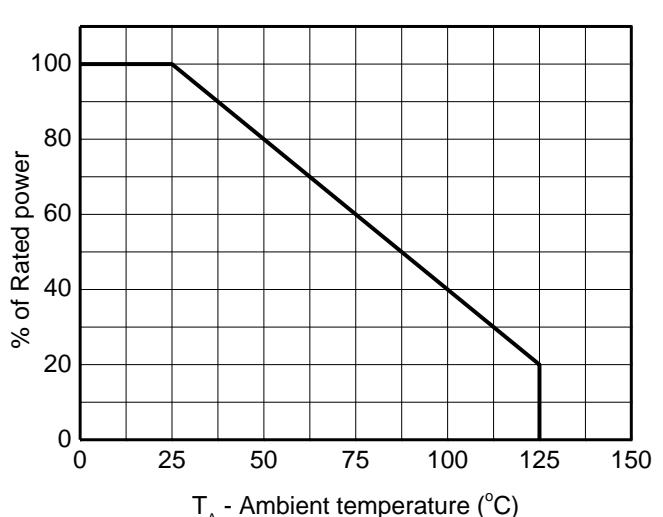
Parameter	Symbol	Rating	Unit
Peak pulse power ( $tp=8/20\mu s$ )	Ppk	36	W
Peak pulse current ( $tp=8/20\mu s$ )	Ipp	3	A
ESD voltage IEC61000-4-2 air	$V_{ESD}$	$\pm 20$	KV
ESD voltage IEC61000-4-2 contact		$\pm 20$	
Junction temperature	$T_J$	125	$^{\circ}C$
Operating temperature	$T_{OP}$	-40~85	$^{\circ}C$
Lead temperature	$T_L$	260	$^{\circ}C$
Storage temperature	$T_{STG}$	-55~150	$^{\circ}C$

**Electronics characteristics (Ta=25 °C, unless otherwise noted)**

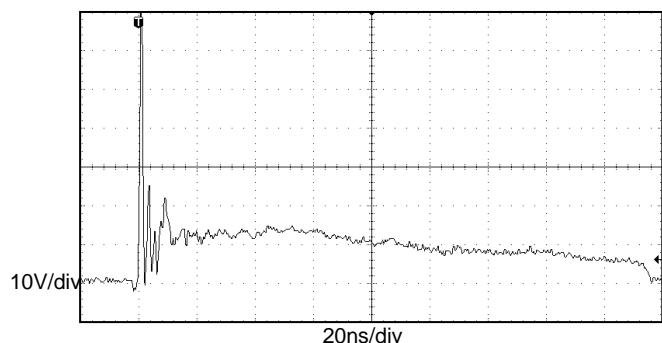
Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Reverse stand-off voltage	$V_{RWM}$				5.0	V
Reveres leakage current	$I_R$	$V_{RWM}=5V$			1.0	$\mu A$
Breakdown voltage	$V_{BR}$	$I_T=1mA$	6.5		8.2	V
Clamping voltage <sup>1)</sup>	$V_{CL}$	$I_{PP} = 16A, t_p = 100ns$		13		V
Clamping voltage <sup>2)</sup>	$V_{CL}$	$V_{ESD} = 8kV$		13		V
Clamping voltage <sup>3)</sup>	$V_C$	$I_{PP}=1A tp=8/20\mu s$			8.5	V
		$I_{PP}=3A tp=8/20\mu s$			12	V
Dynamic resistance <sup>1)</sup>	$R_{DYN}$			0.4		$\Omega$
Junction capacitance	$C_J$	$V_R = 0V, f = 1MHz$		5	12	pF

Notes:

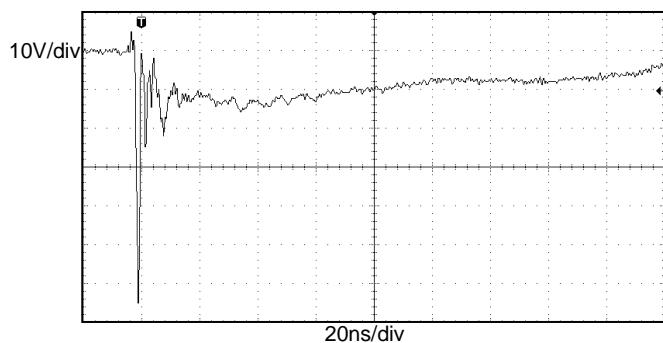
- 1) TLP parameter:  $Z_0 = 50\Omega$ ,  $t_p = 100ns$ ,  $t_r = 2ns$ , averaging window from 60ns to 80ns.  $R_{DYN}$  is calculated from 4A to 16A.
- 2) Contact discharge mode, according to IEC61000-4-2.
- 3) Non-repetitive current pulse, according to IEC61000-4-5.

**Typical characteristics ( $T_A=25^\circ\text{C}$ , unless otherwise noted)**

**8/20μs waveform per IEC61000-4-5**

**Contact discharge current waveform per IEC61000-4-2**

**Clamping voltage vs. Peak pulse current**

**Capacitance vs. Reverse voltage**

**Non-repetitive peak pulse power vs. Pulse time**

**Power derating vs. Ambient temperature**

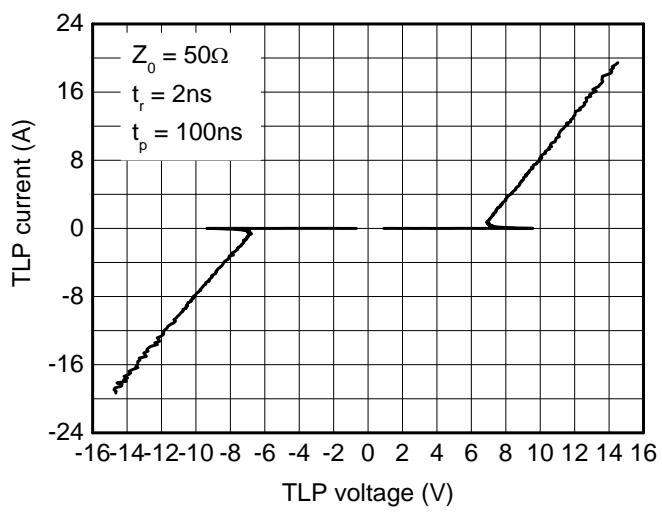
**Typical characteristics ( $T_A=25^\circ\text{C}$ , unless otherwise noted)**



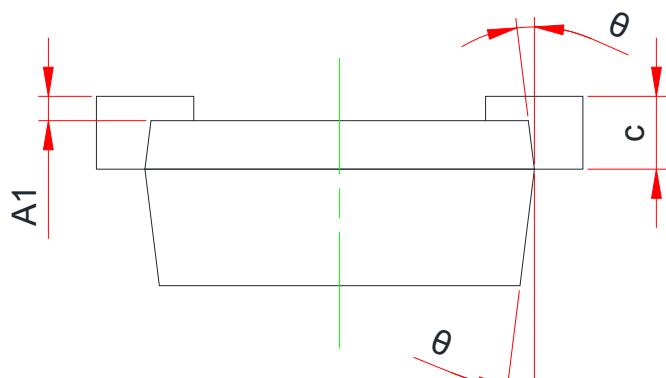
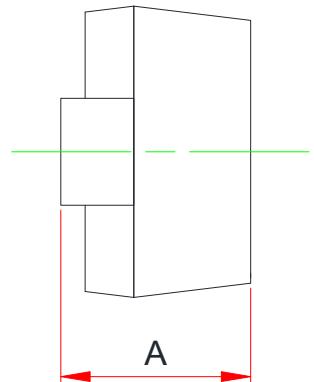
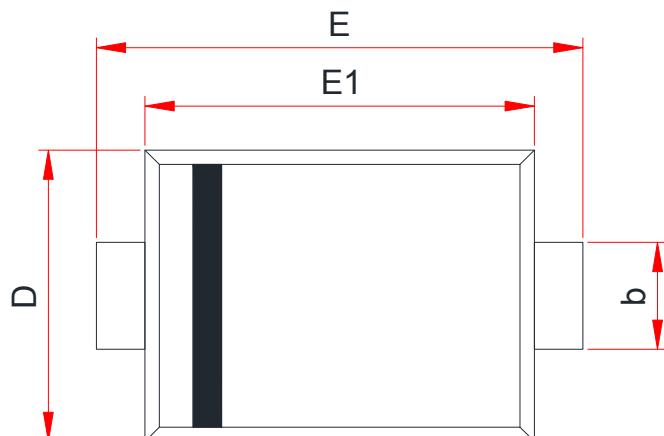
**ESD clamping**  
(+8kV contact discharge per IEC61000-4-2)



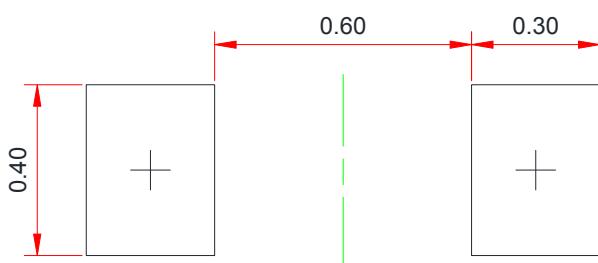
**ESD clamping**  
(-8kV contact discharge per IEC61000-4-2)



**TLP Measurement**

**Package outline dimensions**
**SOD-923**

**Recommend PCB Layout (Unit: mm)**

Symbol	Dimensions in millimeter		
	Min.	Typ.	Max.
A	0.35	-	0.45
A1	0.00	-	0.05
b	0.15	-	0.27
c	-	-	0.18
D	0.55	0.60	0.65
E	0.90	1.00	1.10
E1	0.75	0.80	0.85
$\theta$	7° Ref.		


**Notes:**

This recommended land pattern is for reference purposes only. Please consult your manufacturing group to ensure your PCB design guidelines are met.